ABSTRACT

DEVICE FOR TREATING MICRO-CIRCUIT WAFERS

The invention relates to a device for treating micro-circuit wafers, comprising a feed station for cassettes with wafers, at least one treatment station in which wafer carries and treatment means co-acting therewith are disposed and a transfer station provided with transfering means for removing wafers from the cassettes and placing them in the wafer carriers and, after treatment, removing the wafers from the wafer carriers and replacing them in the cassettes. At least the feed station and the treatment station are embodied as separate connectable units having in cross section an at least partially regular polygonal periphery, wherein these units connect onto other units at the position of the sides of the regular polygonal periphery.

Fig. 1